



<b>Title of Change:</b>	Qualification of Taiko Grind and Backmetal Process at ON Semiconductor Roznov for 1200V IGBT – Ultra Field Stop	
<b>Proposed first ship date:</b>	27 March 2019 or earlier upon customer approval	
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <Dong.Ta@onsemi.com>	
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office or < <a href="mailto:PCN.samples@onsemi.com">PCN.samples@onsemi.com</a> >  Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.	
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <Xiaohu.zhang@onsemi.com>	
<b>Type of notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a> >	
<b>Change Part Identification:</b>	The affected products listed here with date code 1914 and later may have its backside processed out of ON Semiconductor’s facility in Niigata, Japan and Roznov, Czech Republic.	
<b>Change Category:</b>	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
<b>Change Sub-Category(s):</b>	<input checked="" type="checkbox"/> Manufacturing Site Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
<b>Sites Affected:</b>	ON Semiconductor Sites: ON Roznov, Czech Republic	External Foundry/Subcon Sites: None
<b>Description and Purpose:</b>		
This is a final change notification to qualify Taiko grind and back metal process in ON Semiconductor Roznov, Czech Republic, as part of our capacity expansion efforts ensuring competitive business continuity.		
	<b>Before Change Description</b>	<b>After Change Description</b>
Taiko Grind and Back Metal Process	ON Semiconductor Niigata, Japan	ON Semiconductor Niigata, Japan ON Semiconductor Roznov, Czech Republic
Upon the expiration of this notification, ON Semiconductor Roznov will be an additional wafer fab site to our current ON Semiconductor Niigata, Japan, consolidating the Taiko grind and back metal process for selected 1200V IGBT – Ultra Field Stop.		
There will be no change to the orderable part numbers, and all electrical performances are comparable. Data can be provided upon request.		



**Reliability Data Summary:**

W6PST120DA28CNA-FAB (Internal die 80 A – 1200 V Ultra Field Stop technology)

Below is the Reliability for the IGBT respectively.

Test	Specification	Condition	Interval	Results
TC	JESD22-A104	Temp = -65°C to +150°C	1000 cyc	0/160

**Electrical Characteristic Summary:**

Electrical characteristics are not impacted. Data available upon request.

**List of Affected Parts:**

Part Number	Qualification Vehicle
NGTB25N120FL3WG	W6PST120DA28CNA-FAB (Internal die 80 A – 1200 V Ultra Field Stop technology)
NGTB40N120FL3WG	
NGTB40N120L3WG	
NGTB40N120S3WG	
FGY75T120SQDN	
PCFG40T120SQF	
PCFG60T120SQF	
PCFG75T120SQF	
PCFG25T120SQF	
FGY60T120SQDN	
PCRL75120SQF	

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**Appendix A: Changed Products**

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Product	Customer Part Number	Qualification Vehicle
NGTB25N120FL3WG		W6PST120DA28CNA-FAB
NGTB40N120FL3WG		W6PST120DA28CNA-FAB
NGTB40N120L3WG		W6PST120DA28CNA-FAB
NGTB40N120S3WG		W6PST120DA28CNA-FAB